

## Technical Data

# FK 1071

## AgPt Conductor Paste for AlN-Substrates

### Typical Properties <sup>1</sup>

Shrinkage <sup>2</sup> (%)	43 -47		
Fired Thickness (µm)	14 –16		
Resitivity <sup>3</sup> (mOhm/sq)	< 6		
Solderability <sup>4</sup> Sn/Pb/Ag 63/35,5/1,5	> 98		
Leaching Resistance <sup>5</sup>	3 - 4 dips		
Adhesion Strength <sup>4,6</sup>	1 x fired	3 x fired	1 x fired <sup>7</sup>
Initial	> 16 N/4mm <sup>2</sup>	> 15 N/4mm <sup>2</sup>	> 12 N/4mm <sup>2</sup>
Aged 100 h, 150°C	> 16 N/4mm <sup>2</sup>	poor	poor

**Notes:**

<sup>1</sup> Profil: 850°C, 10 min, 60 min Cyclus time

<sup>3</sup> FFT: 15µm

<sup>5</sup> Flux: Alpha 611, 230°C, 5 s

<sup>7</sup> Profile: 850°C, 10 min, 30 min cold to cold

<sup>2</sup> ( dried to fired)

<sup>4</sup> Flux: Alpha 611, 220°C, 5 s

<sup>6</sup> 90 ° wire-peel-test, 2mm x 2mm, L-Sn63Ag1,5

### Recommended Processing Procedure:

**Substrates:** AlN-ANCeram

**Storage:**

Paste should be stored at 4 10°C .  
Allow paste to reach ambient temperature before opening  
Stire thoroughly before use

**Printing:** 200 mesh stainless steel screen  
With 10-12 µm Emulsion.  
Level at Room temperature for 10 min.  
Dry at 150°C for 15-20 min.

**Firing:** In Air, Peaktemperature: 850°C.  
Peak time: 10 min.  
Total Cycle Time : 60 min.

**Thinner:** FK 100

